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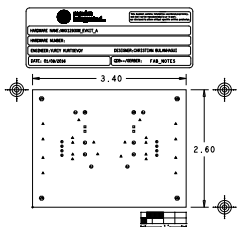
3

2

1

REVISIONS			
REV	DESCRIPTION	APPROVED	DATE


- NOTES:
- UNLESS OTHERWISE SPECIFIED:
    - DIMENSIONS ARE IN INCHES (EXCEPT WHERE NOTED).
    - MATERIAL: (USE CHECKED ITEMS FOR MATERIAL).
  - BOARD MATERIAL:
    - (X) FR4 (RHS COMPLIANT) OR EQUIVALENT
    - ( ) T80A-FR4000
    - ( ) MELCO-4000-13 OR EQUIVALENT
    - ( ) 370HM (RHS COMPLIANT) OR EQUIVALENT
    - ( ) ROGERS 4300B/FR4000
    - ( ) ROGERS 4003C/FR4000
    - ( ) OTHER \_\_\_\_\_
  - THE PCB SHALL BE FABRICATED TO IPC-4002, TYPE X, CLASS 2.
  - WORKMANSHIP SHALL CONFORM TO IPC-A-600, CLASS 2, CURRENT REVISIONS.
  - BOARD MATERIAL & CONSTRUCTION SHALL MEET THE REQUIREMENTS OF ULTRA WITH FLAMMABILITY RATING OF 94V-0.
  - OVERALL BOARD THICKNESS REFER TO LAMINATION DIAGRAM. TOLERANCE APPLIED AFTER ALL LAMINATION AND PLATING PROCESSES. IT IS TO BE MEASURED FROM TOP PCB METAL TO BOTTOM PCB METAL UNLESS OTHERWISE SPECIFIED.
  - ROG & TEST SHOULD BE MEASURED PER IPC-7094-600, METHOD 2.4.20.
- TOOLING: (USE CHECKED ITEMS FOR TOOLING)
- PHOTO EICH CIRCUITRY PER ENCLOSED SEMI-REPEAT OR 00M+ FORMAT FILE. DRILL LOCATION AND SIZE CONTROLLED BY EXCELLENT ONE DRILL FILE.
  - IF STATED IN THE LAMINATION DIAGRAM, THE DIELECTRIC THICKNESS OF ANY CONTROLLED IMPEDANCE LAYER IS FOR REFERENCE ONLY. FINAL ACCEPTANCE SHALL BE DETERMINED BY THOSE LAYERS HAVING A CHARACTERISTIC IMPEDANCE OF +/-10% OHMS AS STATED IN THE LAMINATION DIAGRAM. THE VENDOR CAN MAKE ADJUSTMENTS AS LONG AS THE STATED IMPEDANCE AND OVERALL BOARD THICKNESS IS MAINTAINED. ANY ADJUSTMENT MADE TO TRACE WIDTH OR SPACING MUST HAVE PRIOR WRITTEN APPROVAL FROM MARK.
  - ALL TRACES FILLETED OPTION TO CHANGE RELIABILITY AT PAD JUNCTIONS WHERE SPACING PERMITS. UNLESS OTHERWISE SPECIFIED:
    - ( ) FILLETED
    - (X) NOT FILLETED
  - LAYER TO LAYER REGISTRATION SHALL BE WITHIN .005 INCHES. LEADING TO LEADING +/- 0.001 INCHES.
- FINISH: (USE CHECKED ITEMS FOR PLATING)
- PLATING SPECIFICATION:
    - (X) STARTING COPPER WEIGHT FOR OUTER LAYERS TO BE (1.0Z). THE FINISH COPPER WEIGHT IS (1.0Z). FOR OUTER LAYERS WHERE SPACING PREVENTS THE USE OF (1.0Z) AS A STARTING WEIGHT, THE STARTING WEIGHT CAN BE (0.5.0Z) AS LONG AS THE FINISH COPPER WEIGHT IS (1.0Z) UNLESS OTHERWISE SPECIFIED.
    - (X) STARTING COPPER WEIGHT FOR OUTER LAYERS TO BE (1.0Z). THE FINISH COPPER WEIGHT IS (1.0Z). FOR OUTER LAYERS WHERE SPACING PREVENTS THE USE OF (1.0Z) AS A STARTING WEIGHT, THE STARTING WEIGHT CAN BE (0.5.0Z) AS LONG AS THE FINISH COPPER WEIGHT IS (1.0Z). UNLESS OTHERWISE SPECIFIED.
    - (X) STARTING COPPER WEIGHT FOR OUTER LAYERS TO BE (2.0Z). THE FINISH COPPER WEIGHT IS (2.0Z) MINIMUM. FOR OUTER LAYERS WHERE SPACING PREVENTS THE USE OF (2.0Z) AS A STARTING WEIGHT, THE STARTING WEIGHT CAN BE (1.0Z) AS LONG AS THE FINISH COPPER WEIGHT IS (2.0Z). UNLESS OTHERWISE SPECIFIED.
    - ( ) OTHER \_\_\_\_\_
  - CHECK ALL THAT APPLY:
    - (X) ELECTROPOSITED HARD GOLD PLATE, TYPE 1 (99.7% MIN GOLD), GRADE C (ENOP HARDNESS 150-200); CLASS 3 (50-100 MICRO INCHES THICK) IN ACCORDANCE WITH MIL-A-45204C. GENERAL SURFACING REQUIREMENTS MUST MEET ANSI/IPC-A-600-CURRENT REV) SECTION 4.5, CLASS 3 (50-100 MICROINCHES THICK) OVER ELECTROPOSITED NICKEL PLATE IN ACCORDANCE WITH ANSI/IPC-A-600, SECTION 4.6, CLASS 3 (100-400 MICROINCHES THICK).
    - (X) FINISH CONDUCTOR SURFACES: IMMERSION GOLD, 3-8 MICRO INCHES OVER 100 MICRO INCHES MINIMUM OF ELECTROLESS NICKEL.
    - (X) FINISH CONDUCTOR SURFACES: IMMERSION GOLD, 2-5 MICRO INCHES OVER 110-120 MICRO INCHES MINIMUM OF ELECTROLESS NICKEL.
    - (X) FINISERS TO BE GOLD PLATED.
    - (X) LEAD FREE AND HAS COMPLIANT PLATING.
    - ( ) OTHER \_\_\_\_\_
  - DRILL SIZES ARE FINISHED HOLE SIZES. ALL HOLES SHALL BE LOCATED WITHIN .005 DTP. MINIMUM HOLE: PLATED HOLES SHALL NOT BE ROUGH OR IRREGULAR SO AS TO FINDER PROPER SOLDER WELDING.
  - CHECK ALL THAT APPLY:
    - (X) GREEN SOLDERMASK OVER BARE COPPER/BARE GOLD (BOTH SIDES) WITH LIQUID PHOTO IMAGEABLE INK (LPI) FOR NETWORK.
    - (X) GREEN TATVO P08-4000
    - ( ) OTHER \_\_\_\_\_
  - CHECK ALL THAT APPLY:
    - (X) APPLY SOLDERMASK USING A NON-CONDUCTIVE, WHITE EPOXY BASED INK PER ARTWORK.
    - ( ) OTHER \_\_\_\_\_
  - VENDOR LOGO & DATE CODE REQUIRED IN INK ON BOTTOM SIDE ONLY. DATE CODE FORMAT MUST BE YMM DDYY ONLY.
- TESTING:
- FINAL ELECTRICAL TEST TO BE PERFORMED USING PROVIDED IPC-8358A NETLIST OR 00M+ FORMAT FILE. (REQUIRED UNLESS OTHERWISE SPECIFIED IN QUOTE)
  - THE PCB SHALL HAVE A VERIFICATION STAMP.
  - A TIME DOMAIN REFLECTOMETER REPORT FOR EACH IMPEDANCE CONTROLLED LAYER AND A CERTIFICATE OF COMPLIANCE SHALL BE PROVIDED BY VENDOR AT TIME OF SHIPMENT.
- MISCELLANEOUS:
- IF PRESENT, ALL BLIND/BORED VIAS WITH AN ASPECT RATIO >1:1 TO BE PLATED SHOT WITH COPPER WHEN USED AS VIA-IN-PAD OR AS A STAGGED VIA. BLIND/BORED VIAS WITH AN ASPECT RATIO >1:1 TO BE FILLED WITH NON-CONDUCTIVE EPOXY, UNLESS OTHERWISE SPECIFIED.
  - FOR ALL DRILL INFORMATION REFER TO DRILL CHART.
    - ( ) NON-CONDUCTIVE EPOXY, FILL AND CAP ALL 0.2XXX INCH DRILLED VIAS.
    - ( ) SILVER, FILL AND CAP ALL 0.2XXX INCH DRILLED VIAS.
  - FINISHED SURFACE CONTACTS AND FILLED VIAS TO BE FREE OF ANY PITS, SCRATCHES, PROBE MARKS OR OTHER DEFECTS THAT COULD EFFECT THE APPEARANCE AND PERFORMANCE OF THE CONTACT SURFACE. CONTACTS ARE TO BE AS FLAT AS POSSIBLE. NOT TO EXCEED +/- 0.001" OF FLATNESS.
  - THIEFING:
    - ( ) SUPPLIER MAY ADD THIEFING TO COMPENSATE FOR LOW COPPER DENSITY AREAS ON THIS DESIGN.
    - (X) SUPPLIER MAY NOT ADD THIEFING TO COMPENSATE FOR LOW COPPER DENSITY AREAS ON THIS DESIGN.
  - PENNET:
    - ( ) PERMITS TO BE INSTALLED BY SUPPLIER
    - ( ) PERMITS NOT TO BE INSTALLED BY SUPPLIER
    - (X) NOT APPLICABLE



LAMINATION DIAGRAM					
NUMBER	LAYER	DESCRIPTION	THICKNESS (in.)	FINISH	THICKNESS (in.)
1	TOP	1	TBD	FR4(RHS)/EGIV	FOIL
2	LP_HD	1	TBD	FR4(RHS)/EGIV	
3	LS_PBR	1	TBD	FR4(RHS)/EGIV	
4	BOTTOM	1	TBD	FR4(RHS)/EGIV	FOIL

THE FINISHED PCB THICKNESS TO BE: 0.0025 +/-0.010

DRILL CHART: TOP to BOTTOM				
ALL UNITS ARE IN MILS				
FIGURE	SIZE	TOLERANCE	PLATED	QTY
Δ	18.0	+3.0/-16.0	PLATED	22
□	43.311	+3.0/-3.0	PLATED	4
○	45.276	+3.0/-3.0	PLATED	8
⊖	62.992	+3.0/-3.0	PLATED	8
⊖	70.866	+3.0/-3.0	PLATED	2
⊖	125.0	+3.0/-3.0	PLATED	4

TOLERANCES UNLESS OTHERWISE SPECIFIED			THE INFORMATION CONTAINED IN THIS DOCUMENT IS PROPRIETARY TO MAXIM. THE INFORMATION IN THIS DOCUMENT IS NOT TO BE SHOWN, REPRODUCED, OR DISCLOSED TO ANYONE OUTSIDE OF MAXIM WITHOUT PRIOR WRITTEN PERMISSION FROM MAXIM.		 <b>maxim</b> <b>integrated</b>		
FRACTIONS <i>1/2</i>	DECIMALS XX +/- .01 XXX +/- .005	ANGLES <i>1/2</i>					
MATERIAL:							
SEE NOTES							
FINISH:							
SEE NOTES			DRAWN BY: C.BULANHAGUI    DATE: 01/2016		HARDWARE NAME:  MAX1293XW EVKIT		
			CHECKED BY:	DATE:			
			APPR. BY:	DATE:	HARDWARE NUMBER:  A		
			APPR. BY:	DATE:			
					NOT TO SCALE	TEMPLATE REV.	SHEET 1 OF 1